

Application Serial No. 10/811,768  
Reply to office action of December 21, 2005

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### **Amendments To The Claims**

The listing of claims presented below will replace all prior versions, and listings, of claims in the application.

#### **Listing of claims:**

1. (withdrawn) A method of manufacturing a semiconductor device substrate, said method comprising the steps of:  
  
arranging on a base a temporary fixing member for temporarily fixing an electronic component;  
  
temporarily fixing the electronic component on the base by using the temporary fixing member;  
  
forming a substrate body on the base and the electronic component;  
  
removing at least a portion of the base which portion corresponds to the electronic component, thereby exposing the temporary fixing member; and  
  
removing the temporary fixing member, thereby enabling the electronic component to make an external connection.
2. (withdrawn) The method as claimed in claim 1, wherein the temporary fixing member is made of a metal.
3. (withdrawn) The method as claimed in claim 2, wherein the metal is a low-melting metal.
4. (withdrawn) The method as claimed in claim 1, wherein the temporary fixing member is a sheet member configured to be able to bond the electronic component to

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the base.

5. (withdrawn) The method as claimed in claim 4, wherein the sheet member is a thermo peeling tape.

6. (withdrawn) The method as claimed in claim 4, wherein the sheet member is a water-soluble sheet.

7. (withdrawn) The method as claimed in claim 4, wherein the sheet member is a UV tape.

8. (withdrawn) The method as claimed in claim 1, wherein the temporary fixing member is a liquid adhesive.

9. (withdrawn) The method as claimed in claim 1, wherein the step of removing at least the portion of the base removes the entire base.

10. (currently amended) A semiconductor device substrate, comprising:

~~a base having an opening formed therein;~~

~~an electronic component; and~~

~~a substrate body arranged on said base and holding said electronic component,~~

~~wherein the opening of the base is formed at a portion corresponding to the electronic component, and~~

~~wherein the electronic component includes an electrode made of a single conductive material exposed at the opening.~~

a substrate layer including an insulating layer and an interconnection layer,  
said insulating layer and said interconnection layer being stacked;

an electronic component buried in the insulating layer, a bump being

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formed on said electronic component acting as an electrode of the electronic component; and

a base layer that is in contact with the insulating layer of the substrate layer and having an opening formed at a portion corresponding to the electronic component to expose at least an end of the bump.

11. (currently amended) The semiconductor device substrate as claimed in claim 10, wherein the ~~electrode of said electronic component~~ bump projects through said substrate ~~body and is~~ layer so as to be connectable to an externally provided semiconductor element.

12. (currently amended) The semiconductor device substrate as claimed in claim 10, wherein the ~~electrode of said electronic component~~ bump projects from a surface of said electronic component facing the opening ~~and is~~ so as to be connectable to an externally provided semiconductor element.

13. (currently amended) The semiconductor device substrate as claimed in claim 10, wherein the substrate ~~body~~ layer has a ~~cavity therein adjacent to the opening to which the electrode is exposed~~ depressed portion between the opening and the electronic component to expose the bump.

14. (currently amended) A semiconductor device, comprising:  
a semiconductor device substrate including:  
~~a base having an opening formed therein;~~  
~~an electronic component; and~~  
~~a substrate body arranged on said base and holding said electronic component;~~

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~~wherein the opening of the base is formed at a portion corresponding to the electronic component, and~~

~~wherein the electronic component includes an electrode made of a single conductive material~~

a substrate layer including an insulating layer and an interconnection layer, said insulating layer and said interconnection layer being stacked;

an electronic component buried in the insulating layer, a bump being formed on said electronic component acting as an electrode of the electronic component; and

a base layer that is in contact with the insulating layer of the substrate layer and having an opening formed at a portion corresponding to the electronic component to expose at least an end of the bump; and

a semiconductor element mounted on said semiconductor device substrate and electrically connected to the **electrode bump** of said electronic component.

15. (currently amended) The semiconductor device as claimed in claim 14, wherein the **electrode bump** of said electronic component projects through said substrate ~~body~~ layer.

16. (currently amended) The semiconductor device as claimed in claim 14, wherein the **electrode bump** of said electronic component projects from a surface of said electronic component that faces the opening.

17. (currently amended) The semiconductor device as claimed in claim 14, wherein the substrate ~~body~~ layer has a ~~cavity therein adjacent to the opening~~ depressed portion between the opening and the electronic component.

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18. (currently amended) A semiconductor device substrate, comprising:
- ~~a base having an opening formed therein;~~
  - ~~an electronic component; and~~
  - ~~a substrate body arranged on said base and holding said electronic component,~~
  - ~~wherein the opening of the base is formed at a portion corresponding to the electronic component,~~
  - ~~wherein the electronic component includes an electrode exposed to the opening, and~~
  - a substrate layer including an insulating layer and an interconnection layer, said insulating layer and said interconnection layer being stacked;
  - an electronic component buried in the insulating layer, a bump being formed on said electronic component acting as an electrode of the electronic component; and
  - a base layer that is in contact with the insulating layer of the substrate layer and having an opening formed at a portion corresponding to the electronic component to expose at least an end of the bump,
  - ~~wherein the substrate body layer has a cavity therein adjacent to the opening to which the electrode is exposed depressed portion between the opening and the electronic component to expose the bump.~~
19. (currently amended) The semiconductor device substrate as claimed in claim 18, wherein the ~~electrode~~ bump projects into the ~~cavity~~ depressed portion.
20. (currently amended) The semiconductor device substrate as claimed in claim 18,

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wherein a top of the ~~electrode~~ bump is substantially uniform with a surface of the substrate ~~body~~ layer that faces the opening of the base layer.

21. (currently amended) A semiconductor device, comprising:

a semiconductor device substrate including:

~~a base having an opening formed therein;~~

~~an electronic component; and~~

~~a substrate body arranged on said base and holding said electronic component,~~

~~wherein the opening of the base is formed at a portion corresponding to the electronic component,~~

~~wherein the electronic component includes an electrode, and~~

a substrate layer including an insulating layer and an interconnection layer, said insulating layer and said interconnection layer being stacked;

an electronic component buried in the insulating layer, a bump being formed on said electronic component acting as an electrode of the electronic component; and

a base layer that is in contact with the insulating layer of the substrate layer and having an opening formed at a portion corresponding to the electronic component to expose at least an end of the bump,

wherein the substrate ~~body~~ layer has a ~~cavity therein adjacent to the opening~~ depressed portion between the opening and the electronic component to expose the bump; and

a semiconductor element mounted on said semiconductor device substrate and

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electrically connected to the ~~electrode~~ bump of said electronic component.

22. (currently amended) The semiconductor device as claimed in claim 21, wherein the ~~electrode~~ bump projects into the ~~cavity~~ depressed portion.

23. (currently amended) The semiconductor device as claimed in claim 21, wherein a ~~top of the electrode is substantially uniform with a surface of the substrate body that faces the opening of the base~~ conductive member is provided between the bump and an electrode of the semiconductor element.